

PATENT ASSIGNMENT

Electronic Version v1.1
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SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
CONVEYING PARTY DATA													
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Juing-Yi Wu</td> <td>09/04/2013</td> </tr> <tr> <td>Jyh-Kang Ting</td> <td>09/04/2013</td> </tr> <tr> <td>Tsung-Chieh Tsai</td> <td>09/04/2013</td> </tr> <tr> <td>Liang-Yao Lee</td> <td>09/04/2013</td> </tr> </tbody> </table>		Name	Execution Date	Juing-Yi Wu	09/04/2013	Jyh-Kang Ting	09/04/2013	Tsung-Chieh Tsai	09/04/2013	Liang-Yao Lee	09/04/2013		
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<table border="1"> <tr> <td>Name:</td> <td>Taiwan Semiconductor Manufacturing Company Limited</td> </tr> <tr> <td>Street Address:</td> <td>No. 8, Li-Hsin Road 6</td> </tr> <tr> <td>Internal Address:</td> <td>Hsin-Chu Science Park</td> </tr> <tr> <td>City:</td> <td>Hsin-Chu</td> </tr> <tr> <td>State/Country:</td> <td>TAIWAN</td> </tr> <tr> <td>Postal Code:</td> <td>300-77</td> </tr> </table>		Name:	Taiwan Semiconductor Manufacturing Company Limited	Street Address:	No. 8, Li-Hsin Road 6	Internal Address:	Hsin-Chu Science Park	City:	Hsin-Chu	State/Country:	TAIWAN	Postal Code:	300-77
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PROPERTY NUMBERS Total: 1													
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CORRESPONDENCE DATA													
<p>Fax Number: 2163733450 <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i></p> <p>Phone: 2166540090 Email: docketing@cooperlegalgroup.com Correspondent Name: Cooper Legal Group LLC Address Line 1: 6505 Rockside Road Suite 330 Address Line 4: Independence, OHIO 44131</p>													
ATTORNEY DOCKET NUMBER:	TSMC2013-0554												
NAME OF SUBMITTER:	Daniel A. Tate												
Signature:	/Daniel A. Tate/												

OP \$40.00 14023751

Date:	09/11/2013
Total Attachments: 2 source=Assignment#page1.tif source=Assignment#page2.tif	

TSMC2013-0554

ASSIGNMENT

For good and valuable consideration received of the hereinafter named assignee, receipt of which is hereby acknowledged, the undersigned

Juing-Yi Wu
Hsinchu City, TW

Jyh-Kang Ting
Baoshan Township, TW

Tsung-Chieh Tsai
Chu-Bei City, TW

Liang-Yao Lee
Taoyuan City, TW

NOW, THEREFORE, for and in consideration of our employment and the salary or wages paid to us by Taiwan Semiconductor Manufacturing Company Limited, I/we, Juing-Yi Wu, Jyh-Kang Ting, Tsung-Chieh Tsai and Liang-Yao Lee, by these presents do sell, assign, and transfer unto said Taiwan Semiconductor Manufacturing Company Limited, a corporation organized and existing under the laws of the Republic of China, having its principal place of business at No. 8, Li-Hsin Road 6, Hsin-Chu Science Park, Hsin-Chu, Taiwan 300-77, R.O.C., is desirous of acquiring an interest therein, its successors and assigns, the entire right, title and interest, so far as concerns the United States and the Territories and Possessions thereof and all foreign countries, in and to the inventions entitled

IMPLANT REGION DEFINITION

for which application for United States Letters Patent has been filed on _____ under Serial No. _____, or was executed by the undersigned on the date below and is being filed concurrently herewith, said application for United States Letters Patent, any and all other applications for Letters Patent on said inventions in countries foreign to the United States, including all divisional, renewal, substitute, continuation and Convention applications based in whole or in part upon said inventions or upon said applications, and any and all Letters Patent and reissues and extensions of Letters Patent granted for said inventions or upon said applications, and every priority right that is or may be predicated upon or arise from said inventions, said applications and said Letters Patent; said assignee being hereby authorized to file patent applications in any or all countries on any or all said inventions in the name of the undersigned or in the name of said assignee or otherwise as said assignee may deem advisable, under the International Convention or otherwise; the Commissioner of Patents and Trademarks of the United States of America and the empowered officials of all other governments being hereby authorized to issue or transfer all said Letters Patent to said assignee in accordance herewith; this assignment being under covenant, not only that full power to make the same is had by the undersigned, but also that such assigned right is not encumbered by any grant, license, or other right heretofore given, and that the undersigned will do all acts reasonably serving to assure that said inventions, patent applications and Letters Patent shall be held and enjoyed by said assignee as fully and entirely as the same could have been held and enjoyed by the undersigned if this assignment had not been made, and particularly to execute and deliver to said assignee all lawful documents including petitions, specifications, oaths, assignments, invention disclaimers, and lawful affidavits in form and substance which may be requested by said assignee, to furnish said assignee with all facts relating to said inventions or the history thereof and any and all documents, photographs, models,

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samples or other physical exhibits which may be useful for establishing the facts of conception, disclosure and reduction to practice of said inventions, and to testify in any proceedings relating to said inventions, patent applications and Letters Patent.

<u>Juing-Yi Wu</u>	<u>Sep 4 2013</u>
Inventor's Signature	Date
<u>Juing-Yi Wu</u>	
Printed Name in English	

<u>Jyh-Kang Ting</u>	<u>2013. 9. 4</u>
Inventor's Signature	Date
<u>Jyh-Kang Ting</u>	
Printed Name in English	

<u>Tsung-Chieh Tsai</u>	<u>Sep 4 2013</u>
Inventor's Signature	Date
<u>Tsung-Chieh Tsai</u>	
Printed Name in English	

<u>Liang-Yao Lee</u>	<u>Sep 4 2013</u>
Inventor's Signature	Date
<u>Liang-Yao Lee</u>	
Printed Name in English	